

150V N-Channel MOSFET

Product Summary

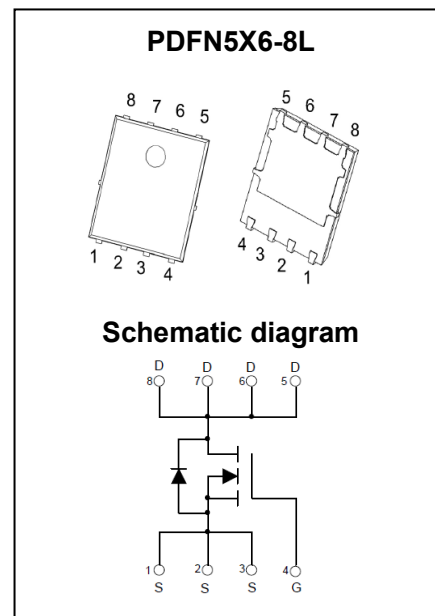
| $V_{(BR)DSS}$ | $R_{DS(on)TYP}$ | I_D |
|---------------|---------------------|-------|
| 150V | 11.5m Ω @10V | 70A |

Feature

- Split Gate Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power Switching Application
- Hard Switched and High Frequency Circuits
- DC/DC Converter



Package Marking and Ordering Information

| Part Number | Package | Marking | Packing | Reel Size | Tape Width | Qty |
|-------------|------------|----------|-------------|-----------|------------|---------|
| T105N15NNC | PDFN5X6-8L | T105N15N | Reel & Tape | 330mm | 12mm | 5000pcs |

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

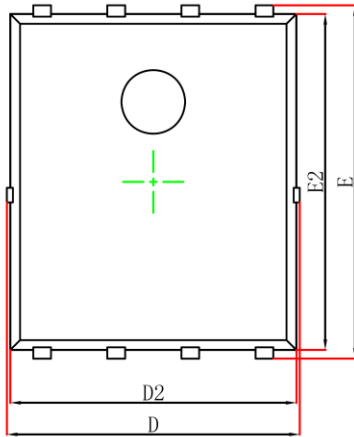
| Parameter | Symbol | Value | Unit |
|--|---------------------------|-----------|---------------------------|
| Drain - Source Voltage | V_{DS} | 150 | V |
| Gate - Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current ¹ | $T_C = 25^\circ\text{C}$ | I_D | 70 |
| | $T_C = 100^\circ\text{C}$ | I_D | 44 |
| Pulsed Drain Current ² | I_{DM} | 280 | A |
| Single Pulsed Avalanche Current ³ | I_{AS} | 40 | A |
| Single Pulsed Avalanche Energy ³ | E_{AS} | 400 | mJ |
| Power Dissipation ⁵ | $T_C = 25^\circ\text{C}$ | P_D | 104 |
| Thermal Resistance from Junction to Ambient ⁶ | $R_{\theta JA}$ | 60 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance from Junction to Case | $R_{\theta JC}$ | 1.2 | $^\circ\text{C}/\text{W}$ |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55~ +150 | $^\circ\text{C}$ |

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

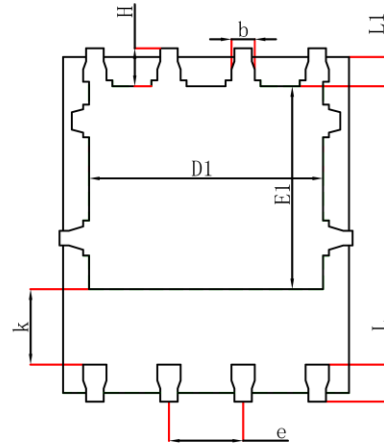
| Parameter | Symbol | Test Condition | Min | Type | Max | Unit |
|---|---------------|---|-----|------|-----------|------------|
| Off Characteristics | | | | | | |
| Drain - Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 250\mu A$ | 150 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 150V, V_{GS} = 0V$ | | | 1 | μA |
| Gate - Body Leakage Current | I_{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | | | ± 150 | nA |
| On Characteristics⁴ | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 2 | 3 | 4 | V |
| Drain-source On-resistance | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 20A$ | | 11.5 | 15 | m Ω |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 75V, V_{GS} = 0V, f = 1MHz$ | | 2240 | | pF |
| Output Capacitance | C_{oss} | | | 256 | | |
| Reverse Transfer Capacitance | C_{rss} | | | 3.2 | | |
| Gate Resistance | R_g | $V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$ | | 2.8 | | Ω |
| Switching Characteristics | | | | | | |
| Total Gate Charge | Q_g | $V_{DS} = 75V, V_{GS} = 10V, I_D = 20A$ | | 31 | | nC |
| Gate-source Charge | Q_{gs} | | | 7.3 | | |
| Gate-drain Charge | Q_{gd} | | | 7.2 | | |
| Gate Plateau Voltage | $V_{plateau}$ | | | 4.9 | | V |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD} = 75V, V_{GS} = 10V, I_D = 35A,$ $R_G = 3\Omega$ | | 13 | | ns |
| Turn-on Rise Time | t_r | | | 4 | | |
| Turn-off Delay Time | $t_{d(off)}$ | | | 16 | | |
| Turn-off Fall Time | t_f | | | 3 | | |
| Source - Drain Diode Characteristics | | | | | | |
| Diode Forward Voltage ⁴ | V_{SD} | $V_{GS} = 0V, I_S = 20A$ | | | 1.2 | V |
| Diode Continuous Forward Current ¹ | I_S | $T_C = 25^\circ\text{C}$ | | | 70 | A |
| Diode Pulse Forward Current ² | I_{SM} | $T_C = 25^\circ\text{C}$ | | | 280 | A |
| Diode Reverse Recovery Time | t_{rr} | $I_F = 20A, di/dt = 100A/\mu s$ | | 90 | | ns |
| Diode Reverse Recovery Charge | Q_{rr} | $I_F = 20A, di/dt = 100A/\mu s$ | | 300 | | nC |

Notes :

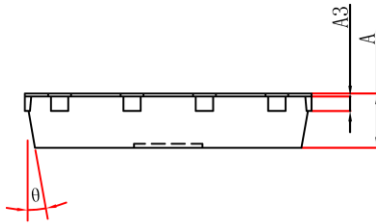
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD} = 100V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.



Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 0.900 | 1.10 | 0.035 | 0.043 |
| A3 | 0.254REF | | 0.010REF | |
| D | 4.700 | 5.260 | 0.185 | 0.207 |
| E | 5.750 | 6.250 | 0.226 | 0.246 |
| D1 | 3.560 | 4.500 | 0.140 | 0.177 |
| E1 | 3.180 | 3.660 | 0.125 | 0.144 |
| D2 | 4.700 | 5.100 | 0.185 | 0.201 |
| E2 | 5.600 | 6.000 | 0.220 | 0.236 |
| k | 1.100 | - | 0.043 | - |
| b | 0.300 | 0.500 | 0.012 | 0.020 |
| e | 1.270TYP | | 0.050TYP | |
| L | 0.510 | 0.710 | 0.020 | 0.028 |
| L1 | 0.424 | 0.576 | 0.017 | 0.023 |
| H | 0.510 | 0.710 | 0.020 | 0.028 |
| θ | 8° | 12° | 8° | 12° |